

03/14/00

04-17-2000

IN THE UNITED S



PK OFFICE

Docket No.: VLSI-3386

101321376

I hereby certify that this transmittal of the below described document is being deposited with the United States Postal Service in an envelope bearing First Class Postage and addressed to the U.S. Patent and Trademark Office, Assignment Branch, North Tower Building, Suite 10C35, Washington, D.C., 20231, on the below date of deposit.

Date of Deposit:	03/14/00	Name of Person Making the Deposit:	RODICA A. DIMA	Signature of the Person Making the Deposit:	<i>Rodica A. Dima</i>
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The Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please record the attached original document(s) or copy(ies) thereof:

Transmittal of an Assignment

1. Name of conveying party(ies): Michael R. Magee, Michael D. Beer, and Wesley R. Erck

Serial No.: 09/473,525

Group Art Unit: 2763

Filed: 12/28/99

Examiner:

2. Name and Address of Receiving party(ies): VLSI TECHNOLOGY, INC.

1109 McKay Drive
San Jose, CA 95131

3. Nature of Conveyance: Assignment

Execution Date: 03/07/2000; 02/29/2000; 03/08/2000

4. New Patent Application entitled: COMPUTATION OF DIE-PER-WAFER CONSIDERING PRODUCTION TECHNOLOGY AND WAFER SIZE

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: John P. Wagner, Jr.

Address: Wagner, Murabito & Hao LLP

Two North Market Street, Third Floor, San Jose, CA 95113

Phone: (408) 938-9060

6. Total Number of applications and patents involved: ONE

7. **Fee Calculation** (for other than a small entity)

Assignment Recordation Fee, per property

1 X \$40.00

Total Fees (37 CFR 3.41)

\$40.00

X The amount of \$ 40.00 is enclosed

8. At any time during the pendency of this application, please charge any additional fees required or credit any overpayments to Deposit Account 23-0085. A duplicate copy of this transmittal is enclosed.

9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: 03/14/2000

Name: John P. Wagner, Jr.

Reg. No. 35,398

04/17/2000 TTOW11 00000221 09473525

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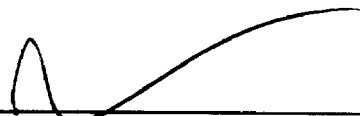
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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: 03/14/2000


Name John P. Wagner, Jr.
Reg. No. 35,398

Assignment to VLSI Technology, Inc.

In consideration of good and valuable consideration, receipt of which is hereby acknowledged, I/we

Michael R. Magee

do hereby sell, assign and transfer unto VLSI Technology, Inc. (hereinafter called VLSI), a California Corporation having its principal place of business at 1109 McKay Drive, San Jose, California 95131, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled:

COMPUTATION OF DIE-PER-WAFER CONSIDERING PRODUCTION TECHNOLOGY AND WAFER SIZE

..... filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; or

X Serial No.: 09/473,525 filed on 12/28/99 and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore;

Further, I/we have agreed to assign to VLSI all inventions (except as otherwise limited by law) which relate to VLSI business and which were first conceived or actually reduced to practice during my/our employment by VLSI;

And for the above consideration, I/we agree promptly upon request of VLSI, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to VLSI, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by VLSI;

I/we further covenant with VLSI, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned;

In witness whereof, I/we hereunto set my/our hand(s) and seal.

Inventor's Signature: Michael R. Magee Date: March 7, 2000

Assignment to VLSI Technology, Inc.

In consideration of good and valuable consideration, receipt of which is hereby acknowledged, I/we

Michael D. Beer

do hereby sell, assign and transfer unto VLSI Technology, Inc. (hereinafter called VLSI), a California Corporation having its principal place of business at 1109 McKay Drive, San Jose, California 95131, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled:

COMPUTATION OF DIE-PER-WAFER CONSIDERING PRODUCTION TECHNOLOGY AND WAFER SIZE

..... filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; or

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And for the above consideration, I/we agree promptly upon request of VLSI, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to VLSI, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by VLSI;

I/we further covenant with VLSI, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned;

In witness whereof, I/we hereunto set my/our hand(s) and seal.

Inventor's Signature:

Michael D. Beer

Date:

February 29, 2000

Assignment to VLSI Technology, Inc.

In consideration of good and valuable consideration, receipt of which is hereby acknowledged, I/we

Wesley R. Erck

do hereby sell, assign and transfer unto VLSI Technology, Inc. (hereinafter called VLSI), a California Corporation having its principal place of business at 1109 McKay Drive, San Jose, California 95131, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled:

COMPUTATION OF DIE-PER-WAFER CONSIDERING PRODUCTION TECHNOLOGY AND WAFER SIZE

..... filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; or

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And for the above consideration, I/we agree promptly upon request of VLSI, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to VLSI, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by VLSI;

I/we further covenant with VLSI, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned;

In witness whereof, I/we hereunto set my/our hand(s) and seal.

Inventor's Signature: W. R. Erck Date: 8-MAR-00